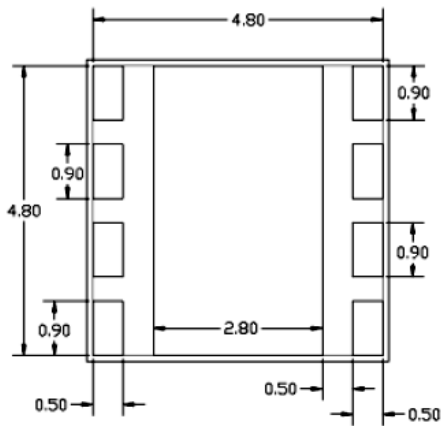
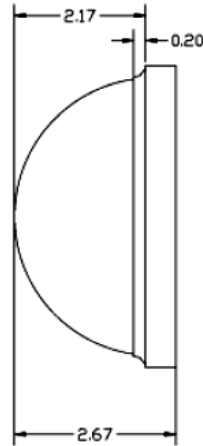
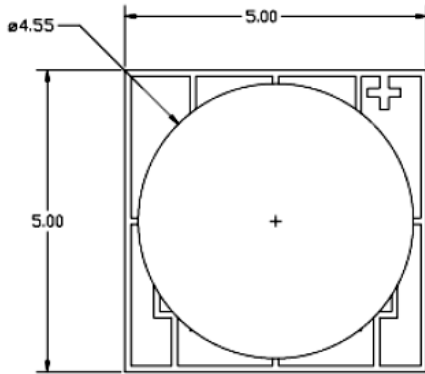


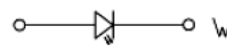
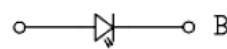
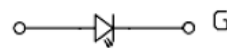
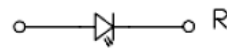
## SPECIFICATION FOR APPROVAL

Part No. : YLE-5050RGBNW-3WMU

### Package Dimensions

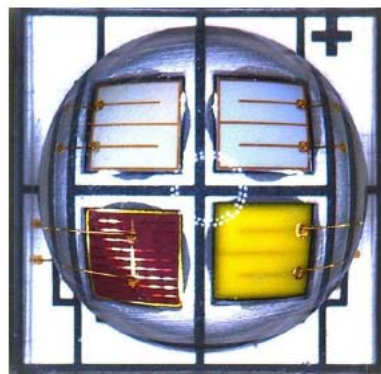


Circuit Diagram



Anode(+)

Cathode(-)



Part NO.	Chip Material				Lens Color	Emission Color
	White	Red	Green	Blue		
YLE-5050RGBNW-3WMU	InGaN	AlGaInP	InGaN	InGaN	Water Clear	White & Red &Green& Blue

#### Notes:

1. All dimensions are in millimeters.
2. Tolerance is  $\pm 0.25\text{mm} (.010\text{'})$  unless otherwise noted.

## ➤ Electrical/Optical Characteristics (IF= 350mA Ta=25°C)

Color	Dominate Wavelength (nm)		Luminous Flux (lm)		Forward Voltage (V)		View angle
	Color Temperature		Radiant Flux (mW)		Min.	Max.	
	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Red</b>	<b>620 nm</b>	<b>630 nm</b>	<b>50 lm</b>	<b>80 lm</b>	<b>2.0</b>	<b>2.8</b>	140°
<b>Green</b>	<b>520 nm</b>	<b>535 nm</b>	<b>90 lm</b>	<b>130 lm</b>	<b>3.0</b>	<b>3.6</b>	
<b>Blue</b>	<b>450 nm</b>	<b>460 nm</b>	<b>450 mW</b>	<b>550 mW</b>	<b>3.0</b>	<b>3.6</b>	
<b>White</b>	<b>5300K</b>	<b>8000K</b>	<b>80 lm</b>	<b>120 lm</b>	<b>3.0</b>	<b>3.6</b>	

## ➤ Absolute Maximum Rating (Ta=25°C)

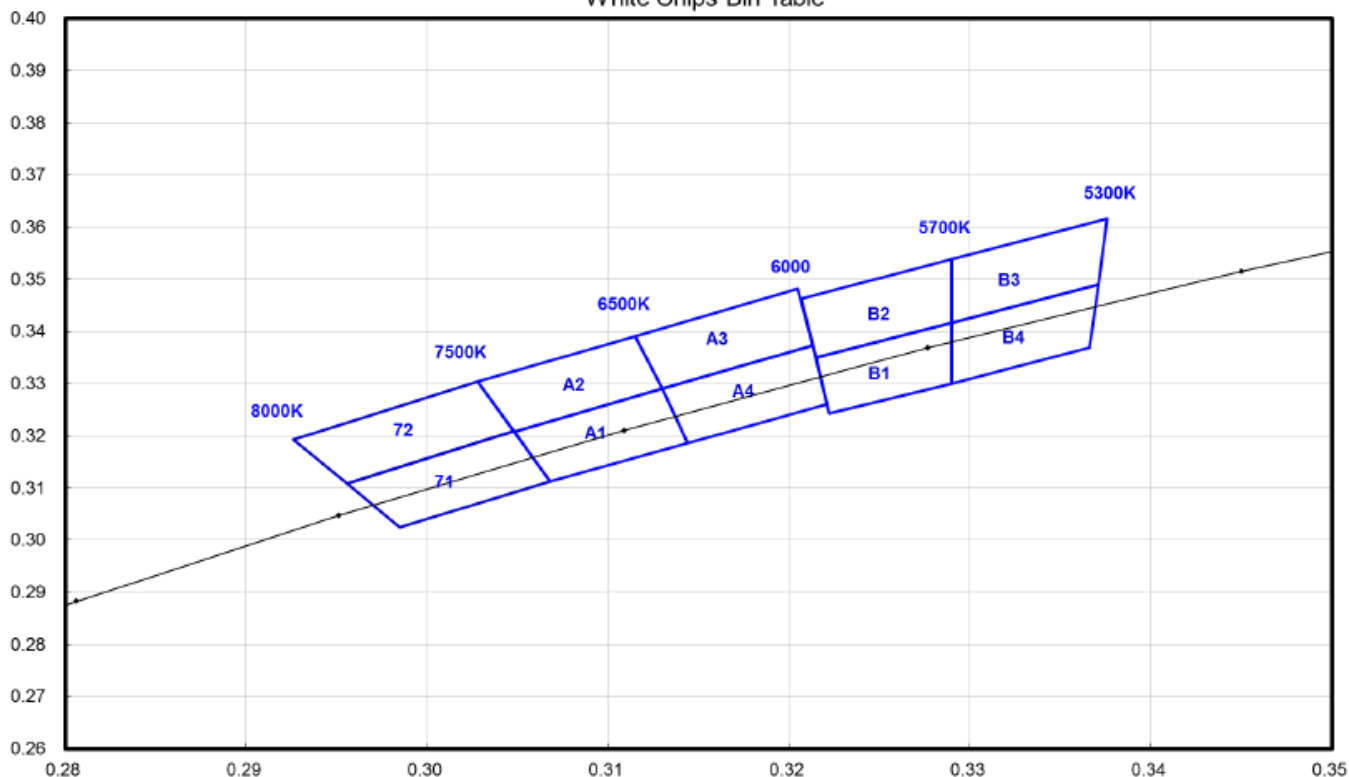
Parameter	Symbol	Ratings	Units
Power Dissipation	P <sub>D</sub>	10	W
Continuous Forward Current-Red	I <sub>F</sub>	1000	mA
Continuous Forward Current-Green	I <sub>F</sub>	1000	mA
Continuous Forward Current-Blue	I <sub>F</sub>	1000	mA
Continuous Forward Current-White	I <sub>F</sub>	1000	mA
Operating Temperature Range	T <sub>OPR</sub>	-30°C To +80°C	
Storage Temperature Range	T <sub>STG</sub>	-40°C To +100°C	
Manual Soldering Temperature	T <sub>SOL</sub>	260°C±20°C For 3-5 Seconds	

### Notes

[1]. Tolerance Ⓟ:10°

## BIN Structure

White Chips Bin Table



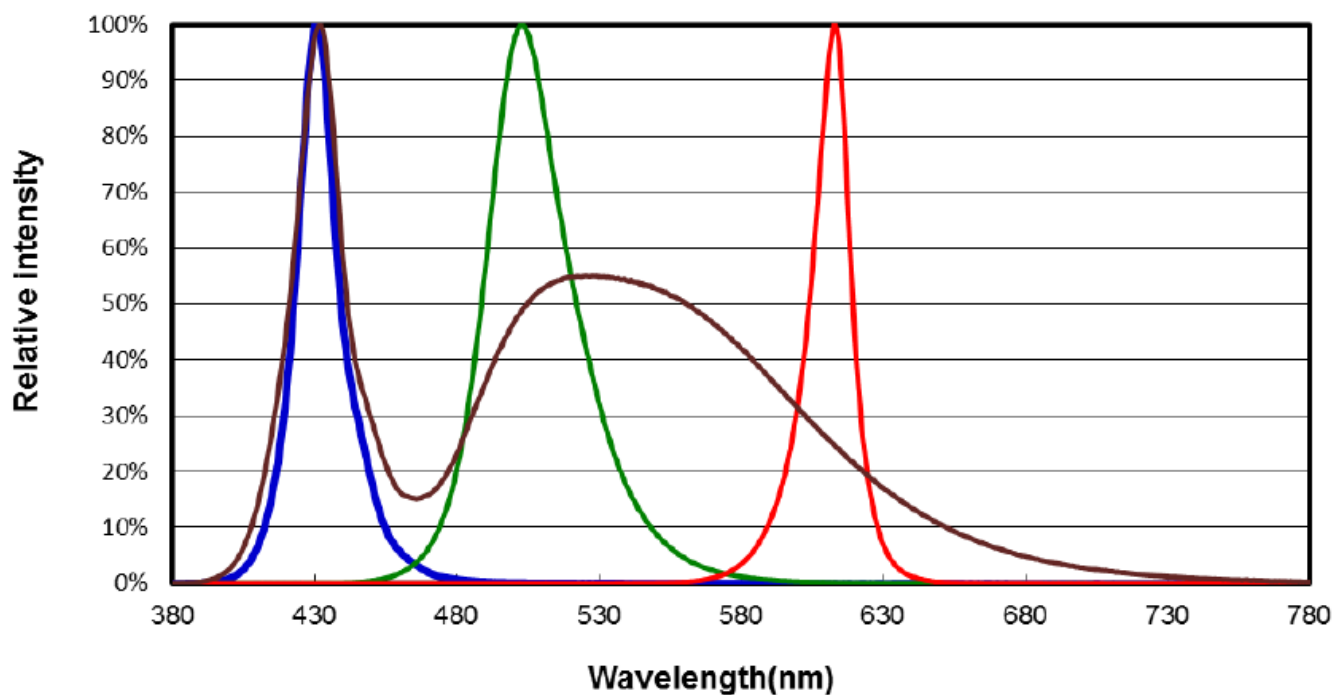
## Bin Coordinates

CCT	分檔代碼	x	y
5650~6000	B1	0.3215	0.3350
		0.3290	0.3417
		0.3290	0.3300
		0.3222	0.3243
	B2	0.3207	0.3462
		0.3290	0.3538
5300~5650	B3	0.3290	0.3538
		0.3376	0.3616
		0.3371	0.3490
		0.3290	0.3417
	B4	0.3290	0.3417
		0.3371	0.3490
		0.3366	0.3369
		0.3290	0.3300

CCT	分檔代碼	x	y
6500~7000	A1	0.3048	0.3207
		0.3130	0.3290
		0.3144	0.3186
		0.3068	0.3113
	A2	0.3028	0.3304
		0.3115	0.3391
6000~6500	A3	0.3130	0.3290
		0.3048	0.3207
		0.3115	0.3391
		0.3205	0.3481
	A4	0.3213	0.3373
		0.3130	0.3290
		0.3213	0.3373
		0.3221	0.3261
		0.3144	0.3186

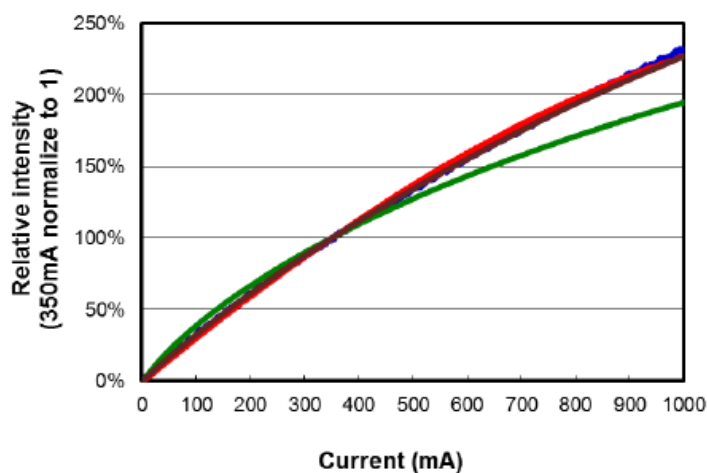
CCT	分檔代碼	x	y
7000~8000	71	0.2926	0.3193
		0.2956	0.3109
		0.3048	0.3209
		0.3028	0.3304
	72	0.2956	0.3109
		0.2985	0.3025
		0.3068	0.3113
		0.3048	0.3209

**Spectrum Distribution**

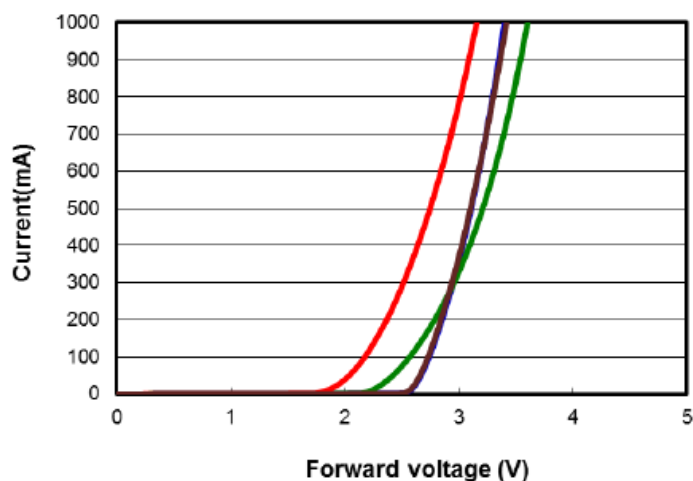


**Characteristic Curves**

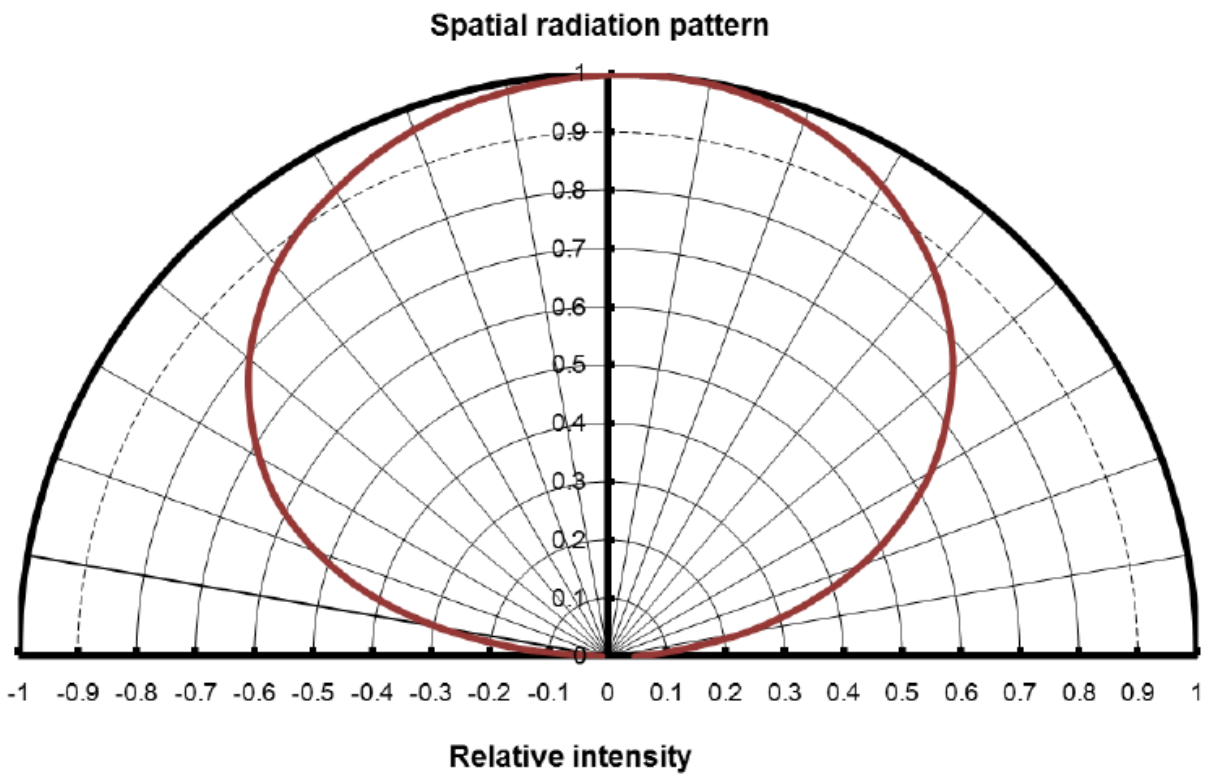
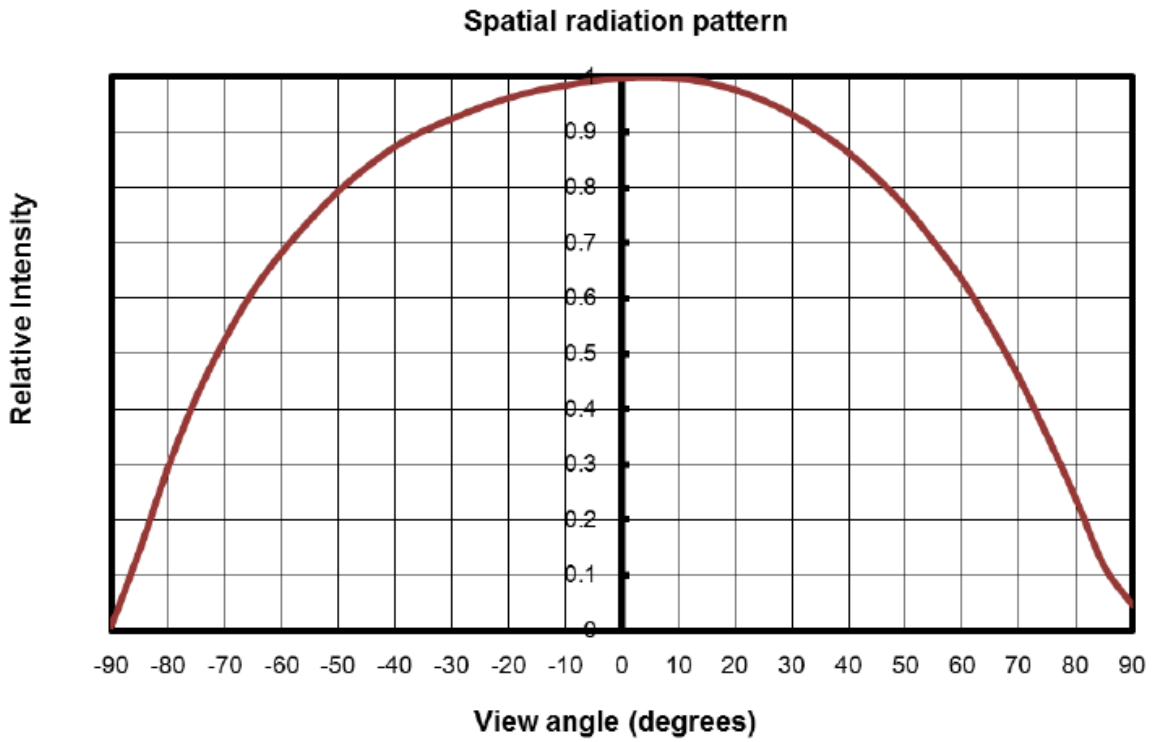
Luminous flux ( $\Phi_v$ ) vs Current ( $I_F$ )



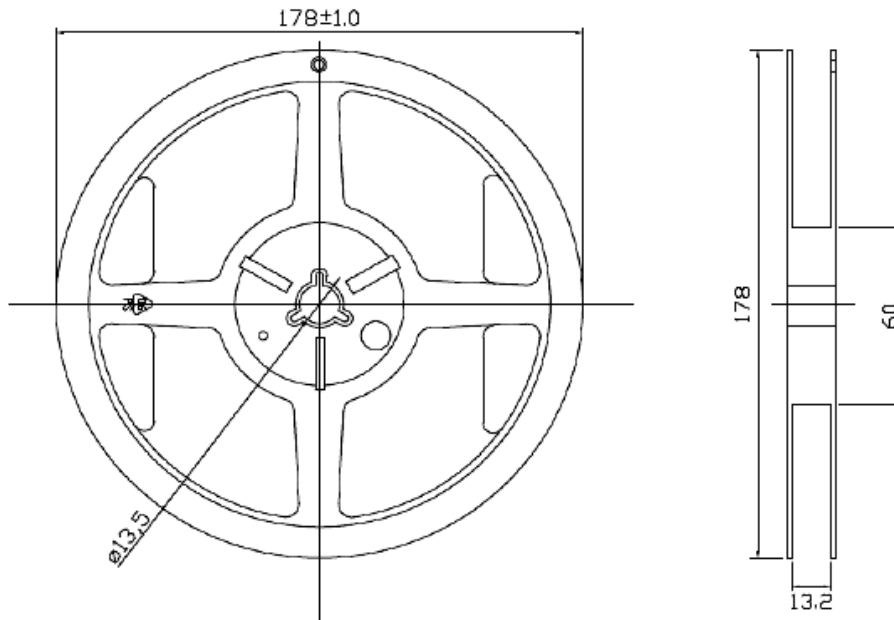
Current ( $I_F$ ) vs Voltage ( $V_F$ )



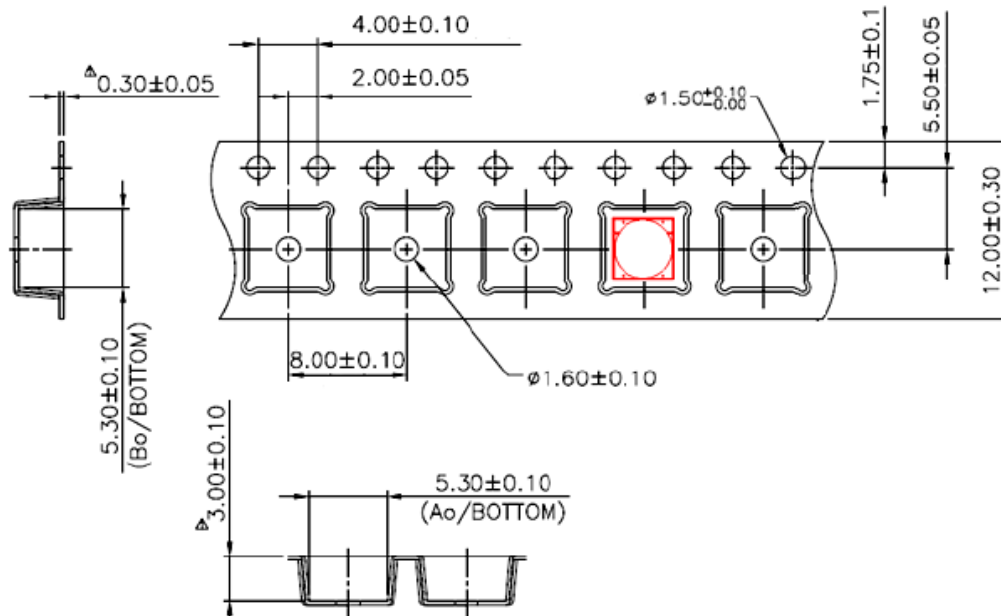
➤ Typical Radiation Pattern



- Packing  
Tape-and-Reel packing
- Reel dimensions



- Carrier tape dimensions



Unit : mm

## ☞ Notice

1. In order to avoid absorption of moisture, it is recommended that the products are stored in the dry box (or desiccators) with a desiccants. Alternatively the following environment is recommended:  
Storage temperature: 5°C~30°C Humidity: 60% HR max.
2. If the storage conditions are of high humidity the product should be dried before use. Recommended drying conditions: 12 hours at 100°C±5°C
3. Any mechanical force or any excess vibration should be avoided during the cooling process after soldering.
4. Reflow rapidly cooling should be avoided.
5. Components should not be mounted on distorted Printed Circuit Boards.
6. Devices should not contact with any types of fluid, such as water, oil, organic solvents.... etc.
7. The maximum ambient temperature should be taken into consideration when determining the operating current.
8. Devices should be soldered within 7 days after opening the moisture-proof packing.
9. Repack unused product in anti-moisture packing, fold to close any opening and store in a dry place.
10. The appearance and specifications of devices may be modified for improvement without notice.
11. ESD Precautions Static Electricity and surge damages LEDs. It is recommended that wrist bands or anti-electrostatic gloves be used when handling the LEDs. All devices, equipment and machinery should be properly grounded.
12. This product must be driven by constant power supplier.